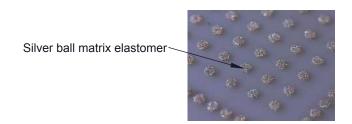
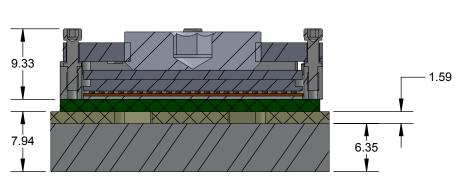
SM-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATION

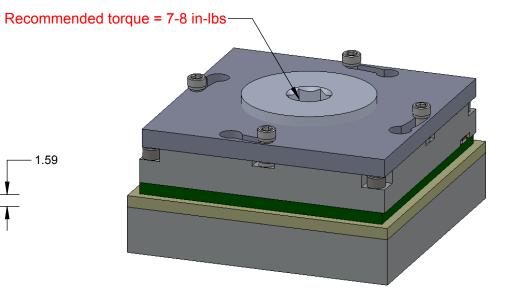
34.325 **TOP VIEW** 34.70

Features

- Wide temperature range (-55C to +150C).
 Current capability is 4A per pin at 14C temperature rise.
 Over 40GHz bandwidth @-1dB for edge pins
 Low and stable contact resistance for reliable production yield.
- Self inductance under 0.21nH.
- Easily removable swivel socket lid







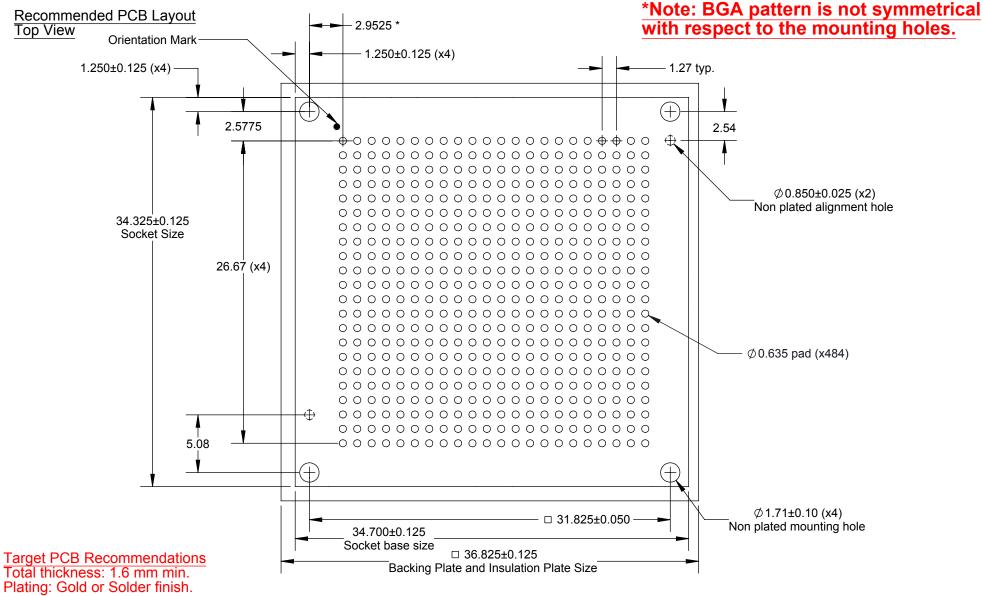
SECTION A-A

Description: Socket Specification

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SM-BGA-9014 Drawing		STATUS: Released	SHEET: 1 OF 4	REV. A
Ironwood Electronics, Inc.	(800) 404-0204 Finish: N/A	DRAWN BY: D. Hauer	SCALE: 2:1	
www.ironwoodelectronics.com		FILE: SM-BGA-9014	DATE: 7/26/2012	



PCB Pad height: Same or higher than solder mask.

NOTE: Steel backing plate may be required based on end user's application.

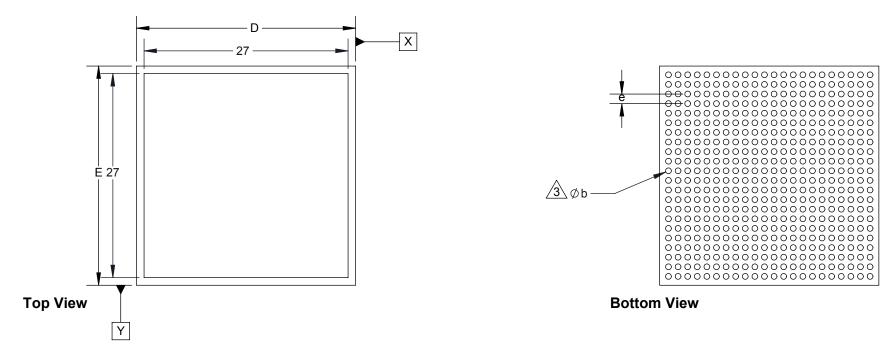
Description: Recommended PCB Layout

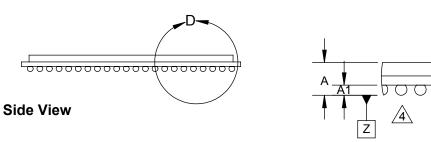
Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SM-BGA-9014 Drawing		STATUS: Released	SHEET: 2 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Tele: (800) 404-0204 Finish: N/A	DRAWN BY: D. Hauer	SCALE: 3:1	
		FILE: SM-BGA-9014	DATE: 7/26/2012	

IRONWOOD PACKAGE CODE: BGA484G





DIM	MIN	MAX	
Α	2.24	2.738	
A1	0.66 after install		
b	0.762 before reflow		
D	29.0 BSC		
Е	29.0 BSC		
е	1.27 BSC		

<u>/</u>5\

DETAIL D SCALE 4:1 Array: 22x22

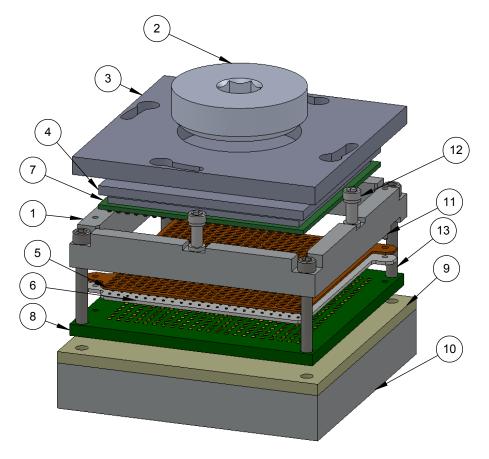
- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5-1994.

Dimension b is measured at the maximum solder bll diameter, parallel to datum plane Z.

Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

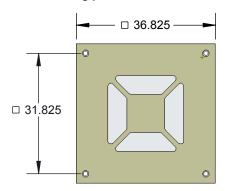
Parallelism measurement shall exclude any effect of mark on top surface of package.

SM-BGA-9014 Drawing		STATUS: Released	SHEET: 3 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A	DRAWN BY: D. Hauer	SCALE: 2:1	
	()	(555) 15 1 5=5 1	FILE: SM-BGA-9014	DATE: 7/26/2012



ITEM NO.	DESCRIPTION	Material
1	SM Socket Base for 29x29mm IC	7075-T6 Aluminum Alloy
2	Compression Screw, M18	7075-T6 Aluminum Alloy
3	Socket Lid	7075-T6 Aluminum Alloy
4	Compression Plate 28.95 x 1.27mm	7075-T6 Aluminum Alloy
5	Ball Guide, SM, 29mm, 22x22	Kapton Polyimide/Cirlex
6	SM Contactor	Silmat
7	484 pin BGA package, 1.27mm Pitch	Material <not specified=""></not>
8	Test PCB BGA484, 1.27mm pitch 22x22 array	FR4
9	Insualtion Plate	FR4
10	Backing Plate	7075-T6 Aluminum Alloy
11	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel
12	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)
13	#0-80 x 0.5, SH Cap Screw	Material <not specified=""></not>

Insulation and backing plate



Top View



Side View

Description: Socket Assem and Detail

SM-BGA-9014 Drawing		STATUS: Released	SHEET: 4 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A	DRAWN BY: D. Hauer	SCALE: 2.5:1	
		Finish: N/A Weight: 48.05	FILE: SM-BGA-9014	DATE: 7/26/2012